

ADC122S051/ADC122S051Q

2 Channel, 200 kps to 500 kps 12-Bit A/D Converter

General Description

The ADC122S051/ADC122S051Q is a low-power, two-channel CMOS 12-bit analog-to-digital converter with a high-speed serial interface. Unlike the conventional practice of specifying performance at a single sample rate only, the ADC122S051/ADC122S051Q is fully specified over a sample rate range of 200 kps to 500 kps. The converter is based on a successive-approximation register architecture with an internal track-and-hold circuit. It can be configured to accept one or two input signals at inputs IN1 and IN2.

The output serial data is straight binary, and is compatible with several standards, such as SPI™, QSPI™, MICROWIRE, and many common DSP serial interfaces.

The ADC122S051/ADC122S051Q operates with a single supply that can range from +2.7V to +5.25V. Normal power consumption using a +3V or +5V supply is 3.0 mW and 10 mW, respectively. The power-down feature reduces the power consumption to just 0.14 μW using a +3V supply, or 0.32 μW using a +5V supply.

The ADC122S051/ADC122S051Q is packaged in an 8-lead MSOP package. Operation over the industrial temperature range of -40°C to +85°C is guaranteed.

Features

- Specified over a range of sample rates.
- Two input channels
- Variable power management
- Single power supply with 2.7V - 5.25V range
- Tested per AEC-Q100 and qualified for automotive applications
- Meets AEC-Q100-011 C2 CDM classification

Key Specifications

- DNL +0.7 / -0.4 LSB (typ)
- INL ± 0.50 LSB (typ)
- SNR 72.5 dB (typ)
- Power Consumption
 - 3V Supply 3.0 mW (typ)
 - 5V Supply 10 mW (typ)

Applications

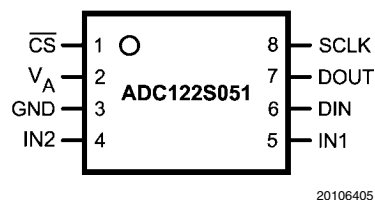
- Portable Systems
- Remote Data Acquisition
- Instrumentation and Control Systems

Pin-Compatible Alternatives by Resolution and Speed

All devices are fully pin and function compatible.

Resolution	Specified for Sample Rate Range of:		
	50 to 200 kps	200 to 500 kps	500 kps to 1 Msps
12-bit	ADC122S021	ADC122S051	ADC122S101
10-bit	ADC102S021	ADC102S051	ADC102S101
8-bit	ADC082S021	ADC082S051	ADC082S101

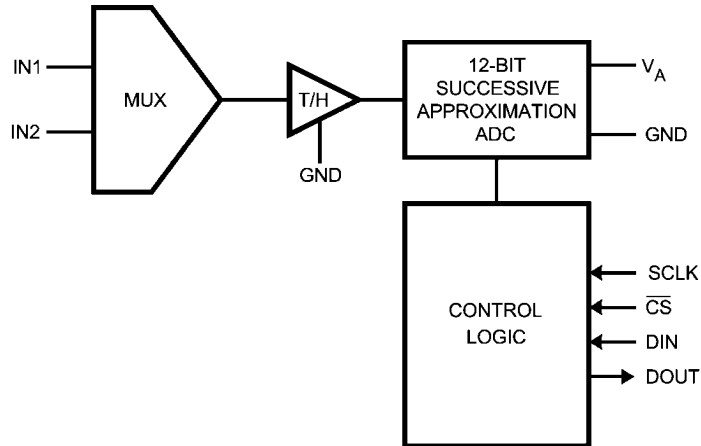
Connection Diagram



Ordering Information

Order Code	Temperature Range	Top Mark	Description
ADC122S051CIMM	-40°C to +85°C	X06C	8-Lead MSOP Package
ADC122S051CIMMX	-40°C to +85°C	X06C	8-Lead MSOP Package, Tape & Reel
ADC122S051QIMM	-40°C to +85°C	X06Q	8-Lead MSOP Package, AEC-Q100 (<i>Note 11</i>)
ADC122S051QIMMX	-40°C to +85°C	X06Q	8-Lead MSOP Package, Tape & Reel, AEC-Q100 (<i>Note 11</i>)
ADC122S051EVAL			Evaluation Board

Block Diagram



20106407

Pin Descriptions and Equivalent Circuits

Pin No.	Symbol	Description
ANALOG I/O		
5,4	IN1 and IN2	Analog inputs. These signals can range from 0V to V_A .
DIGITAL I/O		
8	SCLK	Digital clock input. This clock directly controls the conversion and readout processes.
7	DOUT	Digital data output. The output samples are clocked out of this pin on falling edges of the SCLK pin.
6	DIN	Digital data input. The ADC122S051/ADC122S051Q's Control Register is loaded through this pin on rising edges of the SCLK pin.
1	\overline{CS}	Chip select. On the falling edge of \overline{CS} , a conversion process begins. Conversions continue as long as \overline{CS} is held low.
POWER SUPPLY		
2	V_A	Positive supply pin. This pin should be connected to a quiet +2.7V to +5.25V source and bypassed to GND with a 1 μ F capacitor and a 0.1 μ F monolithic capacitor located within 1 cm of the power pin.
3	GND	The ground return for the die.

Absolute Maximum Ratings (Note 1, Note 2)

If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

Analog Supply Voltage V_A	-0.3V to 6.5V
Voltage on Any Pin to GND	-0.3V to V_A +0.3V
Input Current at Any Pin <small>(Note 3)</small>	±10 mA
Package Input Current <small>(Note 3)</small>	±20 mA
Power Consumption at $T_A = 25^\circ\text{C}$	See <small>(Note 4)</small>
ESD Susceptibility <small>(Note 5)</small>	
Human Body Model	2500V
Machine Model	250V
Charged Device Model	500V
Junction Temperature	+150°C
Storage Temperature	-65°C to +150°C

Operating Ratings (Note 1, Note 2)

Operating Temperature Range	$-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$
V_A Supply Voltage	+2.7V to +5.25V
Digital Input Pins Voltage Range	-0.3V to V_A
Clock Frequency	50 kHz to 16 MHz
Analog Input Voltage	0V to V_A

Package Thermal Resistance

Package	θ_{JA}
8-lead MSOP	250°C / W

Soldering process must comply with National Semiconductor's Reflow Temperature Profile specifications. Refer to www.national.com/packaging. (Note 6)

ADC122S051/ADC122S051Q Converter Electrical Characteristics (Note 9)

The following specifications apply for $V_A = +2.7\text{V}$ to 5.25V , $GND = 0\text{V}$, $f_{SCLK} = 3.2\text{ MHz}$ to 8 MHz , $f_{SAMPLE} = 200\text{ kpsps}$ to 500 kpsps , $C_L = 35\text{ pF}$ unless otherwise noted. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX}** : all other limits $T_A = 25^\circ\text{C}$.

Symbol	Parameter	Conditions	Typical	Limits <small>(Note 7)</small>	Units
STATIC CONVERTER CHARACTERISTICS					
	Resolution with No Missing Codes			12	Bits
INL	Integral Non-Linearity		±0.5	±1.1	LSB (max)
DNL	Differential Non-Linearity		+0.7	1.3	LSB (max)
			-0.4	-1.0	LSB (min)
V_{OFF}	Offset Error		+0.3	±1.3	LSB (max)
OEM	Channel to Channel Offset Error Match		±0.1	±1.0	LSB (max)
FSE	Full Scale Error		-0.5	±1.5	LSB (max)
FSEM	Channel to Channel Full-Scale Error Match		+0.01	±1.0	LSB (max)
DYNAMIC CONVERTER CHARACTERISTICS					
SINAD	Signal-to-Noise Plus Distortion Ratio	$V_A = +2.7$ to 5.25V $f_{IN} = 40.2\text{ kHz}$, -0.02 dBFS	72	69.2	dB (min)
SNR	Signal-to-Noise Ratio	$V_A = +2.7$ to 5.25V $f_{IN} = 40.2\text{ kHz}$, -0.02 dBFS	72.5	70.6	dB (min)
THD	Total Harmonic Distortion	$V_A = +2.7$ to 5.25V $f_{IN} = 40.2\text{ kHz}$, -0.02 dBFS	-84	-75	dB (max)
SFDR	Spurious-Free Dynamic Range	$V_A = +2.7$ to 5.25V $f_{IN} = 40.2\text{ kHz}$, -0.02 dBFS	86	76	dB (min)
ENOB	Effective Number of Bits	$V_A = +2.7$ to 5.25V	11.7	11.2	Bits (min)
	Channel-to-Channel Crosstalk	$V_A = +5.25\text{V}$ $f_{IN} = 40.2\text{ kHz}$	-86		dB
IMD	Intermodulation Distortion, Second Order Terms	$V_A = +5.25\text{V}$, $f_a = 40.161\text{ kHz}$, $f_b = 41.015\text{ kHz}$	-87		dB
	Intermodulation Distortion, Third Order Terms	$V_A = +5.25\text{V}$ $f_a = 40.161\text{ kHz}$, $f_b = 41.015\text{ kHz}$	-88		dB
FPBW	-3 dB Full Power Bandwidth	$V_A = +5\text{V}$	11		MHz
		$V_A = +3\text{V}$	8		MHz

Symbol	Parameter	Conditions	Typical	Limits (Note 7)	Units
ANALOG INPUT CHARACTERISTICS					
V_{IN}	Input Range		0 to V_A		V
I_{DCL}	DC Leakage Current		± 0.02	± 1	μA (max)
C_{INA}	Input Capacitance	Track Mode	33		pF
		Hold Mode	3		pF
DIGITAL INPUT CHARACTERISTICS					
V_{IH}	Input High Voltage	$V_A = +5.25V$		2.4	V (min)
		$V_A = +3.6V$		2.1	V (min)
V_{IL}	Input Low Voltage			0.8	V (max)
I_{IN}	Input Current	$V_{IN} = 0V$ or $V_{IN} = V_A$	± 0.02	± 10	μA (max)
C_{IND}	Digital Input Capacitance		2	4	pF (max)
DIGITAL OUTPUT CHARACTERISTICS					
V_{OH}	Output High Voltage	$I_{SOURCE} = 200 \mu A$	$V_A - 0.03$	$V_A - 0.5$	V (min)
		$I_{SOURCE} = 1 mA$	$V_A - 0.10$		V
V_{OL}	Output Low Voltage	$I_{SINK} = 200 \mu A$	0.02	0.4	V (max)
		$I_{SINK} = 1 mA$	0.1		V
I_{OZH}, I_{OZL}	TRI-STATE® Leakage Current		0.005	± 1	μA (max)
C_{OUT}	TRI-STATE® Output Capacitance		2	4	pF (max)
	Output Coding		Straight (Natural) Binary		
POWER SUPPLY CHARACTERISTICS ($C_L = 10 pF$)					
V_A	Analog Supply Voltage			2.7	V (min)
				5.25	V (max)
I_A	Supply Current, Normal Mode (Operational, \overline{CS} low)	$V_A = +5.25V$, $f_{SAMPLE} = 500 \text{ ksps}$, $f_{IN} = 40 \text{ kHz}$	1.9	2.4	mA (max)
		$V_A = +3.6V$, $f_{SAMPLE} = 500 \text{ ksps}$, $f_{IN} = 40 \text{ kHz}$	0.84	1.2	mA (max)
	Supply Current, Shutdown (\overline{CS} high)	$V_A = +5.25V$, $f_{SAMPLE} = 0 \text{ ksps}$	60		nA
		$V_A = +3.6V$, $f_{SAMPLE} = 0 \text{ ksps}$	38		nA
P_D	Power Consumption, Normal Mode (Operational, \overline{CS} low)	$V_A = +5.25V$	10	12.6	mW (max)
		$V_A = +3.6V$	3.0	4.3	mW (max)
	Power Consumption, Shutdown (\overline{CS} high)	$V_A = +5.25V$	0.32		μW
		$V_A = +3.6V$	0.14		μW
AC ELECTRICAL CHARACTERISTICS					
f_{SCLK}	Maximum Clock Frequency	(Note 8)		3.2	MHz (min)
				8	MHz (max)
f_S	Sample Rate	(Note 8)		200	ksps (min)
				500	ksps (max)
t_{CONV}	Conversion Time			13	SCLK cycles
DC	SCLK Duty Cycle	$f_{SCLK} = 8 \text{ MHz}$	50	30	% (min)
				70	% (max)
t_{ACQ}	Track/Hold Acquisition Time	Full-Scale Step Input		3	SCLK cycles
	Throughput Time	Acquisition Time + Conversion Time		16	SCLK cycles

ADC122S051/ADC122S051Q Timing Specifications

The following specifications apply for $V_A = +2.7V$ to $5.25V$, $GND = 0V$, $f_{SCLK} = 3.2\text{ MHz}$ to 8 MHz , $f_{SAMPLE} = 200\text{ kpsps}$ to 500 kpsps , $C_L = 35\text{ pF}$, **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX}** ; all other limits $T_A = 25^\circ C$.

Symbol	Parameter	Conditions	Typical	Limits (Note 7)	Units	
t_{CSU}	Setup Time SCLK High to \overline{CS} Falling Edge	(Note 10)	$V_A = +3.0V$	-3.5	10	ns (min)
			$V_A = +5.0V$	-0.5		
t_{CLH}	Hold time SCLK Low to \overline{CS} Falling Edge	(Note 10)	$V_A = +3.0V$	+4.5	10	ns (min)
			$V_A = +5.0V$	+1.5		
t_{EN}	Delay from \overline{CS} Until DOUT active		$V_A = +3.0V$	+4	30	ns (max)
			$V_A = +5.0V$	+2		
t_{ACC}	Data Access Time after SCLK Falling Edge		$V_A = +3.0V$	+14.5	30	ns (max)
			$V_A = +5.0V$	+13		
t_{SU}	Data Setup Time Prior to SCLK Rising Edge			+3	10	ns (min)
t_H	Data Valid SCLK Hold Time			+3	10	ns (min)
t_{CH}	SCLK High Pulse Width			$0.5 \times t_{SCLK}$	$0.3 \times t_{SCLK}$	ns (min)
t_{CL}	SCLK Low Pulse Width			$0.5 \times t_{SCLK}$	$0.3 \times t_{SCLK}$	ns (min)
t_{DIS}	\overline{CS} Rising Edge to DOUT High-Impedance	Output Falling	$V_A = +3.0V$	1.8	20	ns (max)
			$V_A = +5.0V$	1.3		
		Output Rising	$V_A = +3.0V$	1.0		
			$V_A = +5.0V$	1.0		

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

Note 2: All voltages are measured with respect to $GND = 0V$, unless otherwise specified.

Note 3: When the input voltage at any pin exceeds the power supply (that is, $V_{IN} < GND$ or $V_{IN} > V_A$), the current at that pin should be limited to 10 mA. The 20 mA maximum package input current rating limits the number of pins that can safely exceed the power supplies with an input current of 10 mA to two. The Absolute Maximum Rating specification does not apply to the V_A pin. The current into the V_A pin is limited by the Analog Supply Voltage specification.

Note 4: The absolute maximum junction temperature (T_{Jmax}) for this device is $150^\circ C$. The maximum allowable power dissipation is dictated by T_{Jmax} , the junction-to-ambient thermal resistance (θ_{JA}), and the ambient temperature (T_A), and can be calculated using the formula $P_{DMAX} = (T_{Jmax} - T_A) / \theta_{JA}$. The values for maximum power dissipation listed above will be reached only when the device is operated in a severe fault condition (e.g. when input or output pins are driven beyond the power supply voltages, or the power supply polarity is reversed). Obviously, such conditions should always be avoided.

Note 5: Human body model is 100 pF capacitor discharged through a 1.5 k Ω resistor. Machine model is 220 pF discharged through zero ohms

Note 6: Reflow temperature profiles are different for lead-free and non-lead-free packages.

Note 7: Tested limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

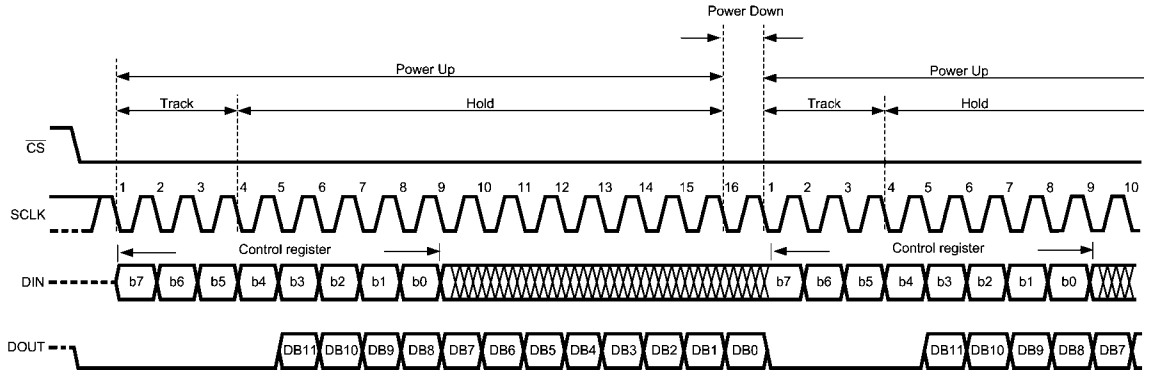
Note 8: This is the frequency range over which the electrical performance is guaranteed. The device is functional over a wider range which is specified under Operating Ratings.

Note 9: Min/max specification limits are guaranteed by design, test, or statistical analysis.

Note 10: Clock may be either high or low when \overline{CS} is asserted as long as setup and hold times t_{CSU} and t_{CLH} are strictly observed.

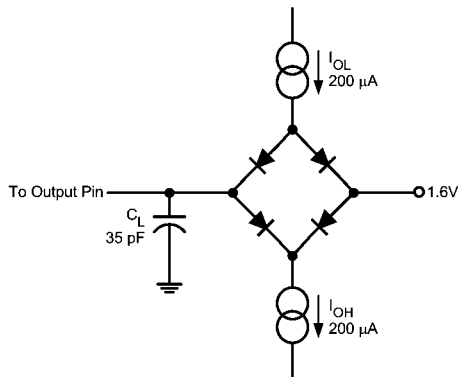
Note 11: PPAP (Production Part Approval Process) documentation of the device technology, process and qualification is available from Texas Instruments upon request.

Timing Diagrams



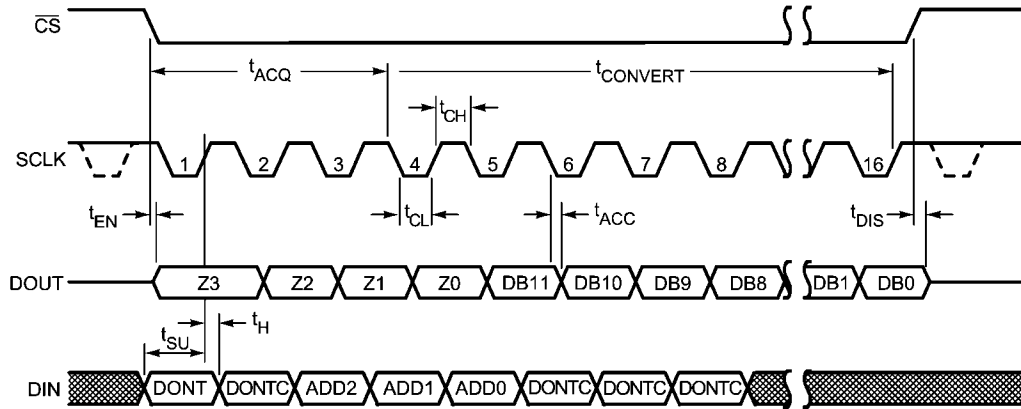
Operational Timing Diagram

20106451



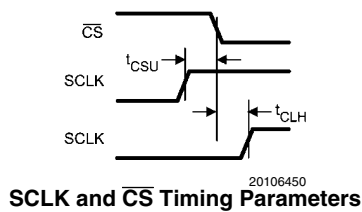
Timing Test Circuit

20106408



Serial Timing Diagram

20106406



SCLK and \overline{CS} Timing Parameters

20106450

Specification Definitions

ACQUISITION TIME is the time required to acquire the input voltage. That is, it is time required for the hold capacitor to charge up to the input voltage.

APERTURE DELAY is the time between the fourth falling SCLK edge of a conversion and the time when the input signal is acquired or held for conversion.

CONVERSION TIME is the time required, after the input voltage is acquired, for the ADC to convert the input voltage to a digital word.

CROSSTALK is the coupling of energy from one channel into the other channel, or the amount of signal energy from one analog input that appears at the measured analog input.

DIFFERENTIAL NON-LINEARITY (DNL) is the measure of the maximum deviation from the ideal step size of 1 LSB.

DUTY CYCLE is the ratio of the time that a repetitive digital waveform is high to the total time of one period. The specification here refers to the SCLK.

EFFECTIVE NUMBER OF BITS (ENOB, or EFFECTIVE BITS) is another method of specifying Signal-to-Noise and Distortion or SINAD. ENOB is defined as $(\text{SINAD} - 1.76) / 6.02$ and says that the converter is equivalent to a perfect ADC of this (ENOB) number of bits.

FULL POWER BANDWIDTH is a measure of the frequency at which the reconstructed output fundamental drops 3 dB below its low frequency value for a full scale input.

FULL SCALE ERROR (FSE) is a measure of how far the last code transition is from the ideal $1\frac{1}{2}$ LSB below V_{REF} , and is defined as:

$$V_{\text{FSE}} = V_{\text{max}} + 1.5 \text{ LSB} - V_{\text{REF}}$$

where V_{max} is the voltage at which the transition to the maximum code occurs. FSE can be expressed in Volts, LSB or percent of full scale range.

GAIN ERROR is the deviation of the last code transition (111...110) to (111...111) from the ideal ($V_{\text{REF}} - 1.5 \text{ LSB}$), after adjusting for offset error.

INTEGRAL NON-LINEARITY (INL) is a measure of the deviation of each individual code from a line drawn from negative full scale ($\frac{1}{2}$ LSB below the first code transition) through positive full scale ($\frac{1}{2}$ LSB above the last code transition). The deviation of any given code from this straight line is measured from the center of that code value.

INTERMODULATION DISTORTION (IMD) is the creation of additional spectral components as a result of two sinusoidal

frequencies being applied to the ADC input at the same time. It is defined as the ratio of the power in the second and third order intermodulation products to the sum of the power in both of the original frequencies. IMD is usually expressed in dB.

MISSING CODES are those output codes that will never appear at the ADC outputs. These codes cannot be reached with any input value. The ADC122S051/ADC122S051Q is guaranteed not to have any missing codes.

OFFSET ERROR is the deviation of the first code transition (000...000) to (000...001) from the ideal (i.e. GND + 0.5 LSB).

SIGNAL TO NOISE RATIO (SNR) is the ratio, expressed in dB, of the rms value of the input signal at the converter output to the rms value of the sum of all other spectral components below one-half the sampling frequency, not including d.c. or harmonics included in the THD specification.

SIGNAL TO NOISE PLUS DISTORTION (S/N+D or SINAD) is the ratio, expressed in dB, of the rms value of the input signal to the rms value of all of the other spectral components below half the clock frequency, including harmonics but excluding d.c.

SPURIOUS FREE DYNAMIC RANGE (SFDR) is the difference, expressed in dB, between the desired signal amplitude to the amplitude of the peak spurious spectral component, where a spurious spectral component is any signal present in the output spectrum that is not present at the input and may or may not be a harmonic.

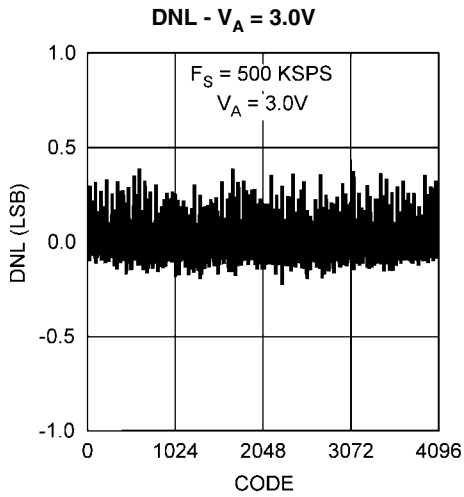
TOTAL HARMONIC DISTORTION (THD) is the ratio, expressed in dB or dBc, of the rms total of the first five harmonic components at the output to the rms level of the input signal frequency as seen at the output. THD is calculated as

$$\text{THD} = 20 \cdot \log_{10} \sqrt{\frac{A_{f_2}^2 + \dots + A_{f_6}^2}{A_{f_1}^2}}$$

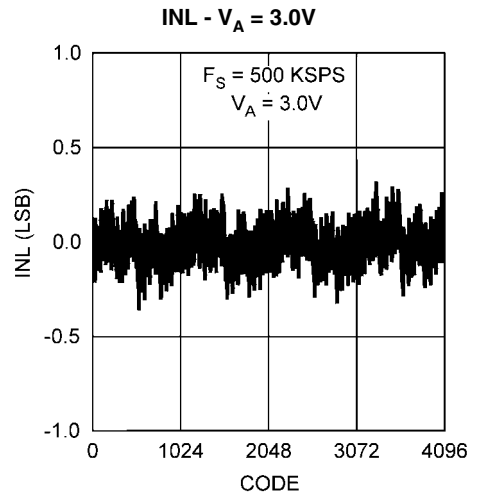
where A_{f_1} is the RMS power of the input frequency at the output and A_{f_2} through A_{f_6} are the RMS power in the first 5 harmonic frequencies. Accurate THD measurement requires a spectrally pure sine wave (monotone) at the ADC input.

THROUGHPUT TIME is the minimum time required between the start of two successive conversion. It is the acquisition time plus the conversion and read out times. In the case of the ADC122S051/ADC122S051Q, this is 16 SCLK periods.

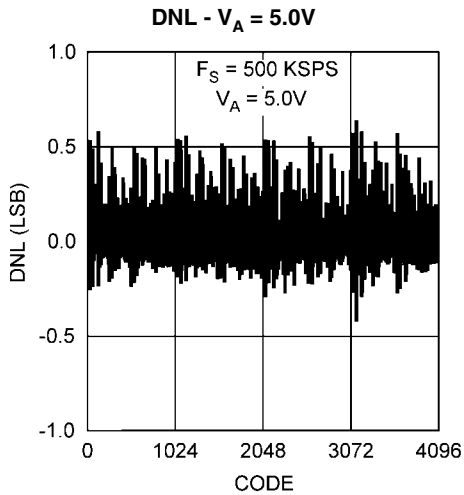
Typical Performance Characteristics $T_A = +25^\circ\text{C}$, $f_{\text{SAMPLE}} = 200 \text{ kpsps to } 500 \text{ kpsps}$, $f_{\text{SCLK}} = 3.2 \text{ MHz to } 8 \text{ MHz}$, $f_{\text{IN}} = 40.2 \text{ kHz}$ unless otherwise stated.



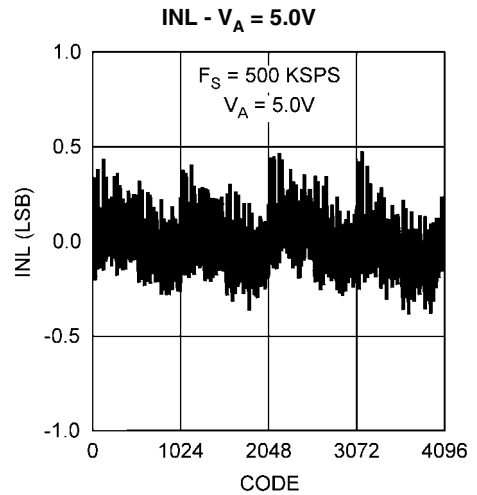
20106420



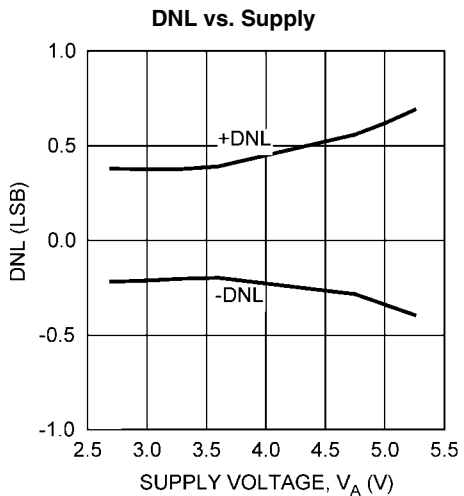
20106421



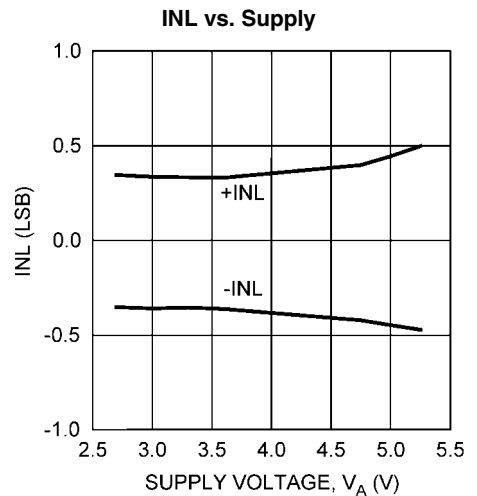
20106462



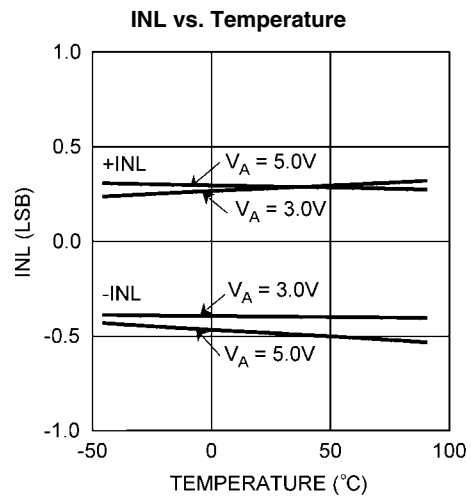
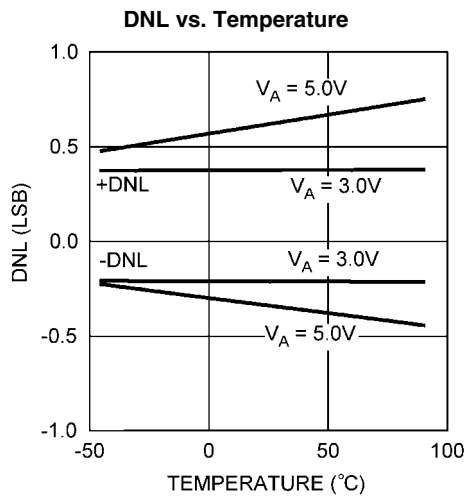
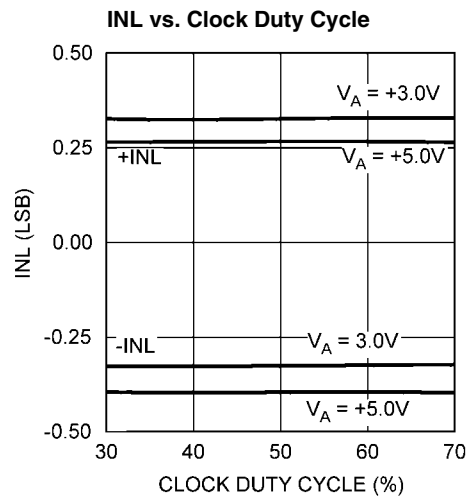
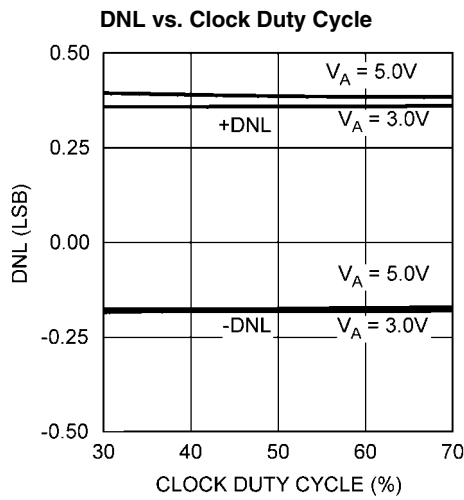
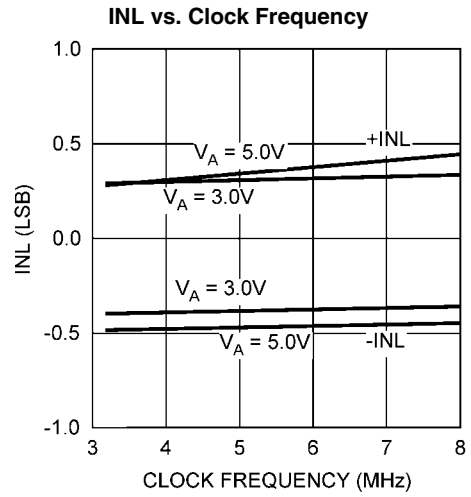
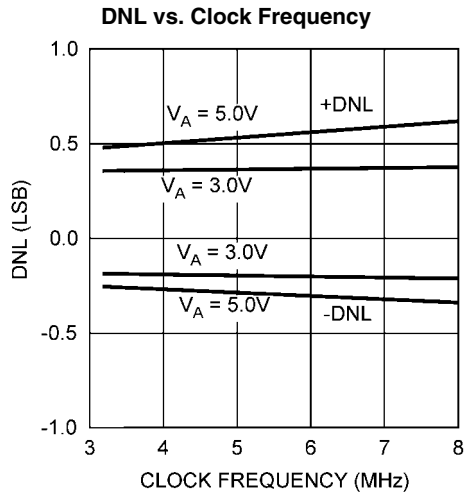
20106463

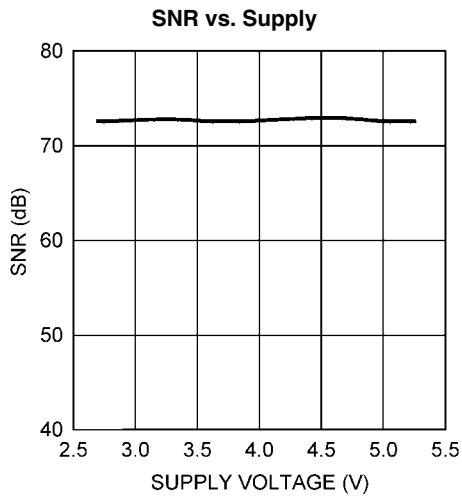


20106422

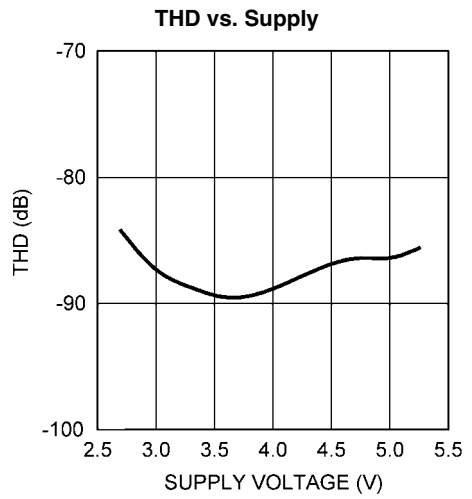


20106423

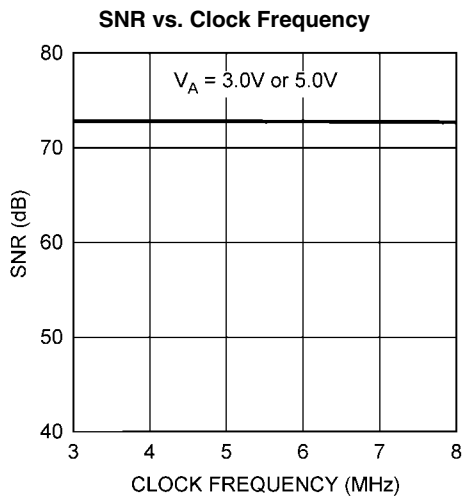




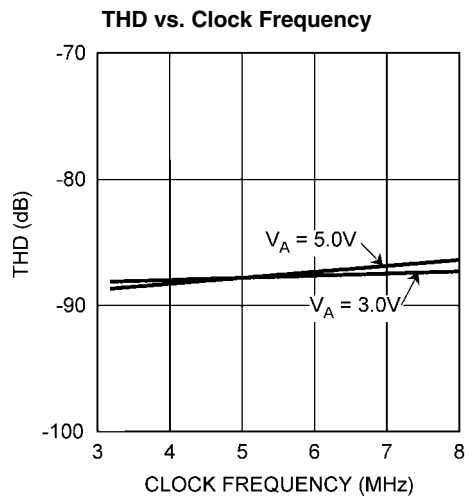
20106430



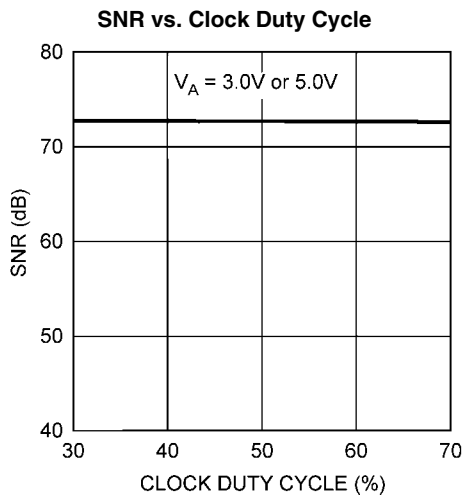
20106435



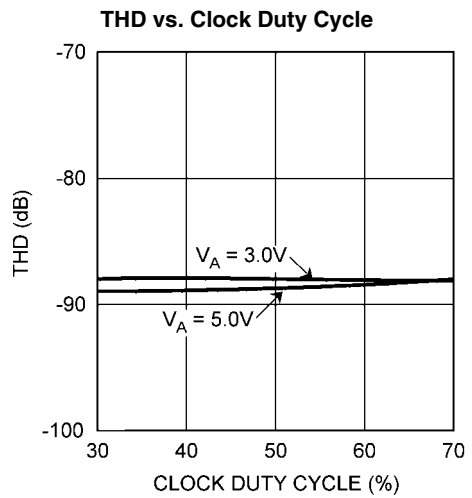
20106431



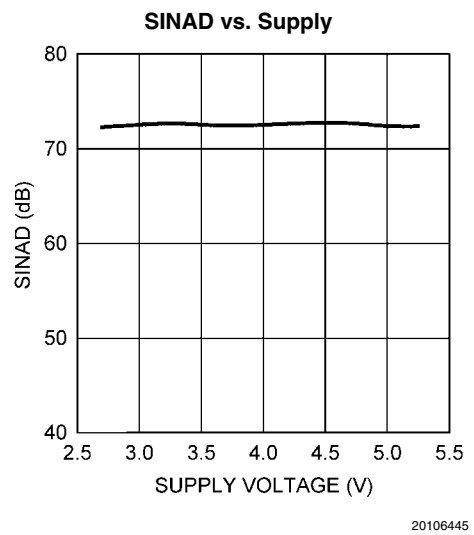
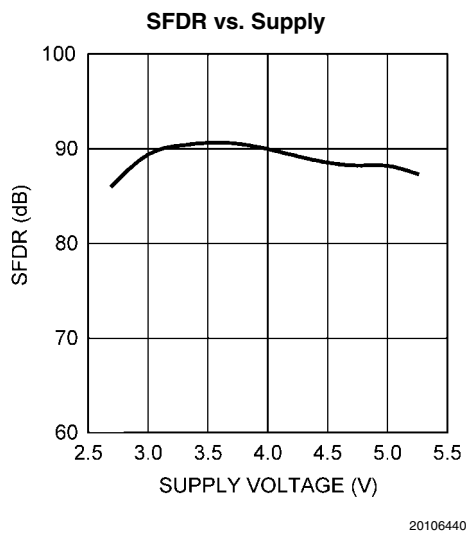
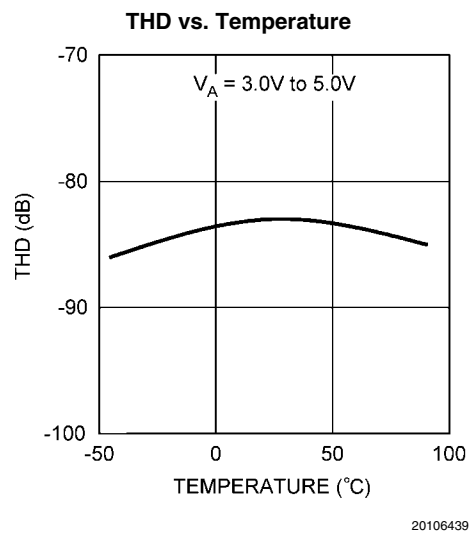
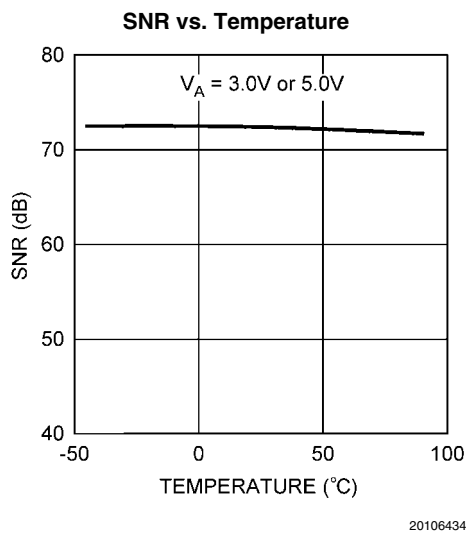
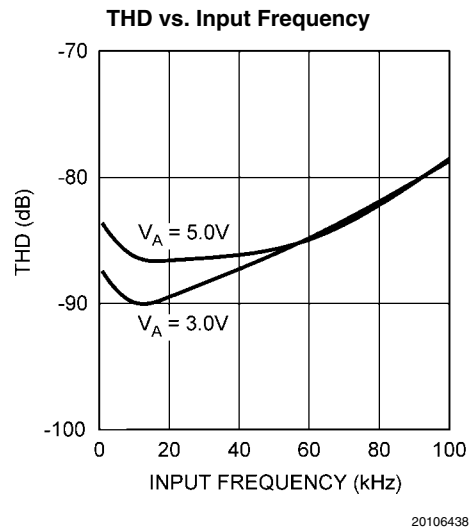
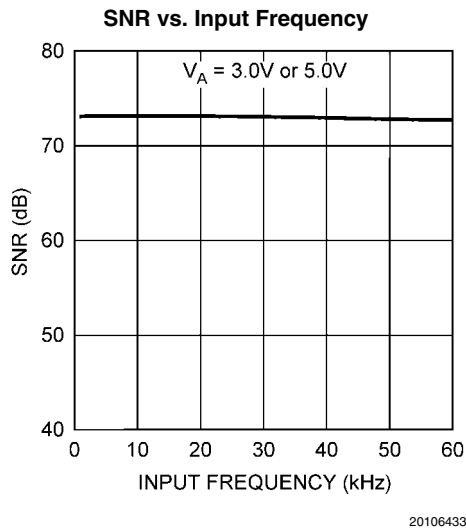
20106436

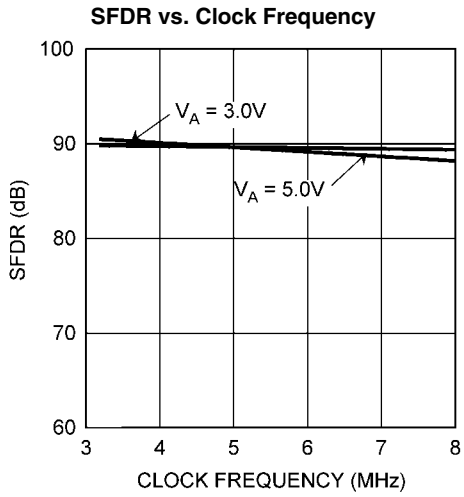


20106432

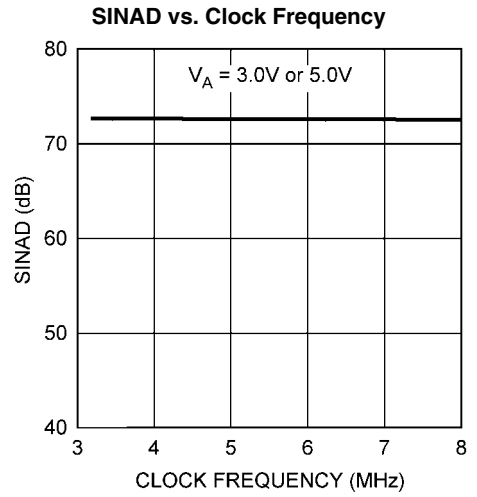


20106437

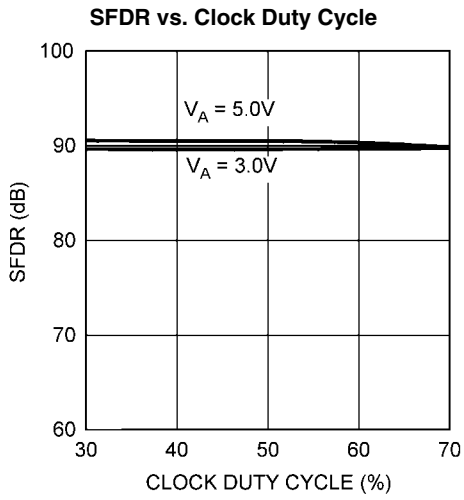




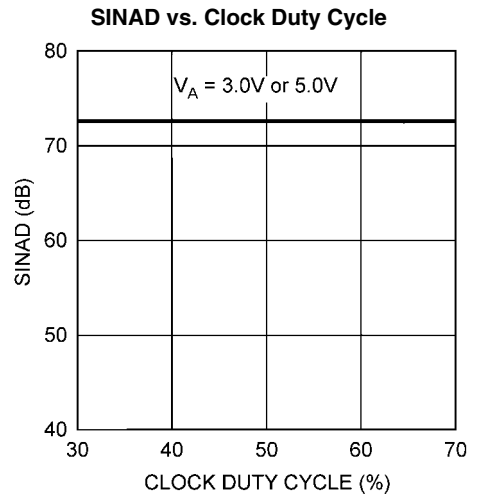
20106441



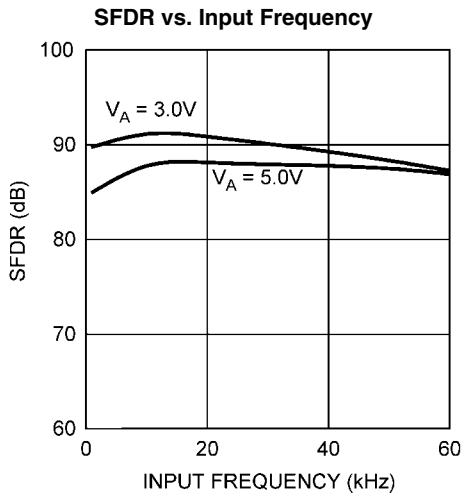
20106446



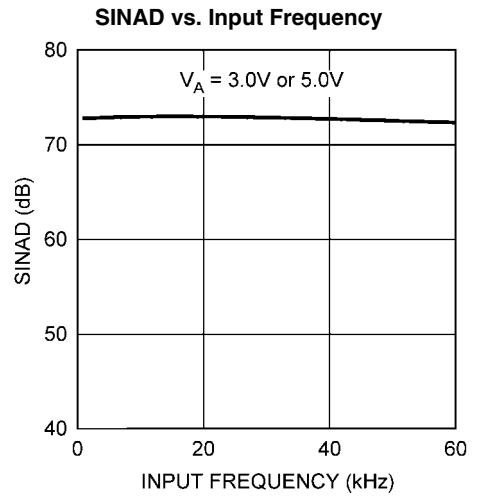
20106442



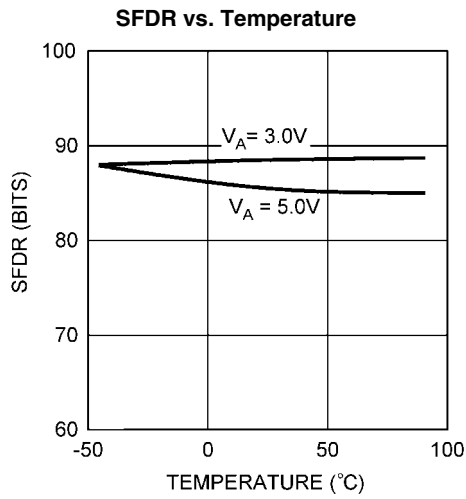
20106447



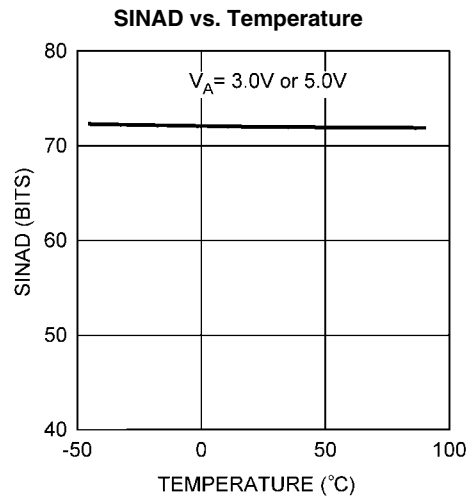
20106443



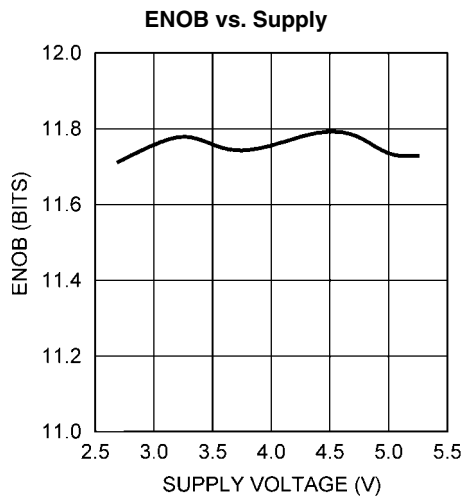
20106448



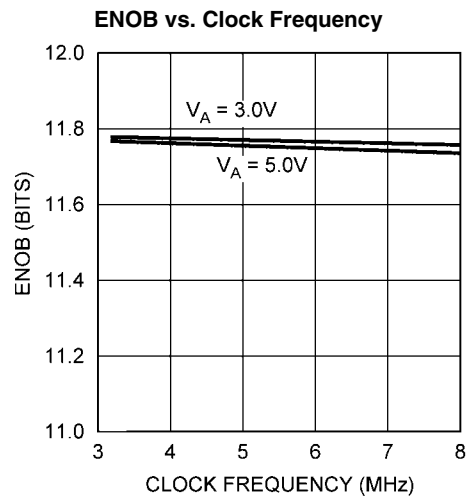
20106444



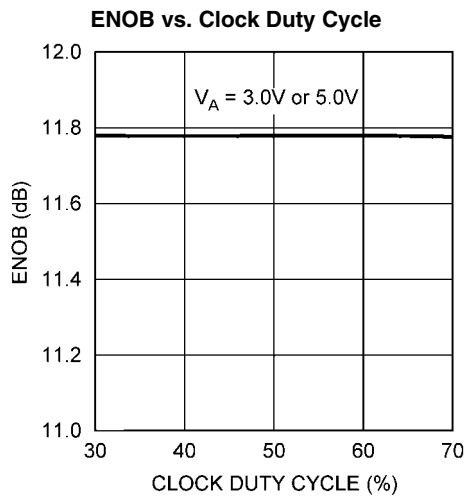
20106449



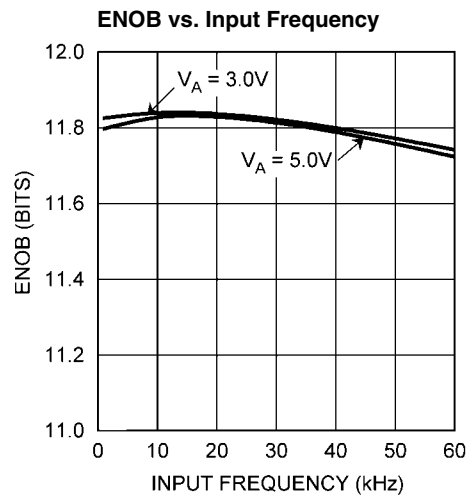
20106452



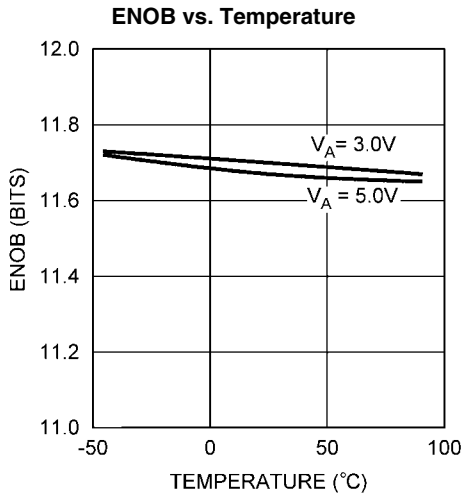
20106453



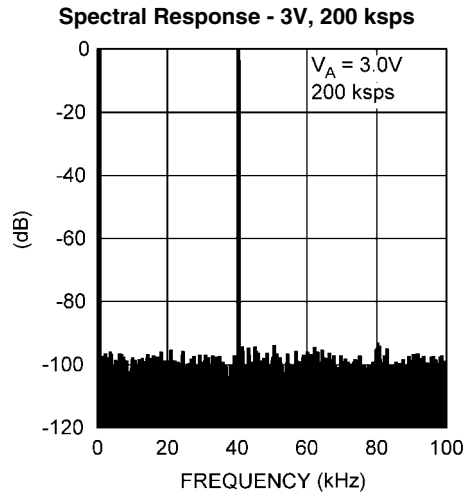
20106454



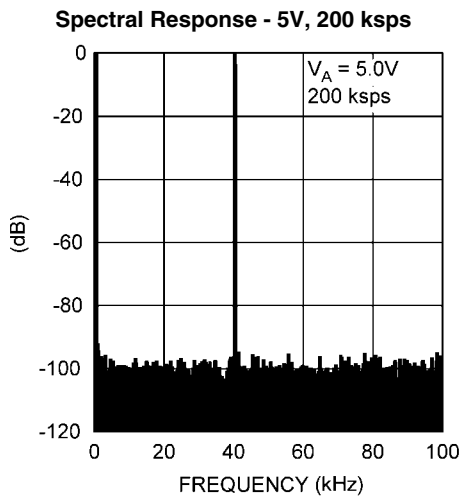
20106455



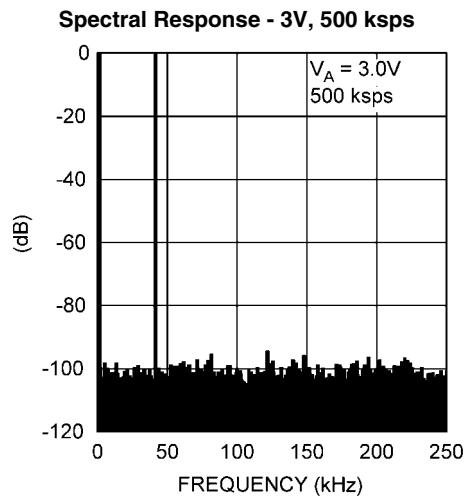
20106456



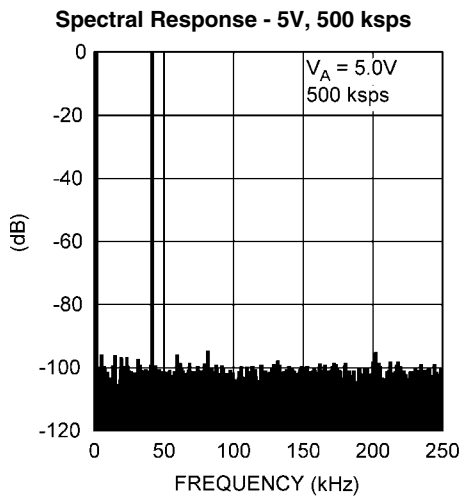
20106459



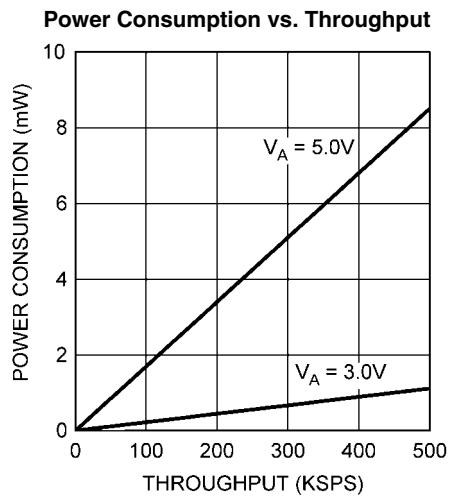
20106460



20106464



20106465



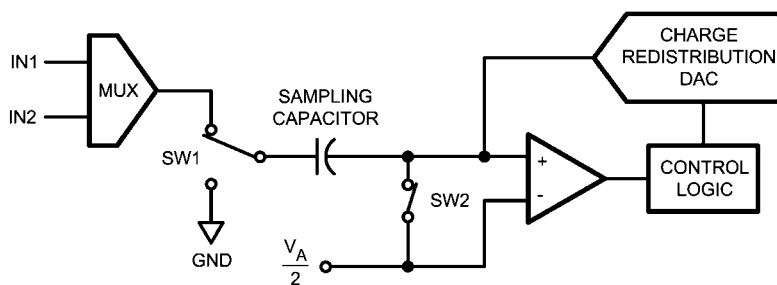
20106461

Applications Information

1.0 ADC122S051/ADC122S051Q OPERATION

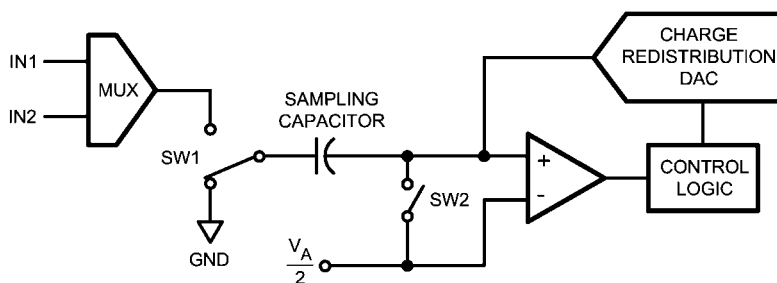
For the rest of this document, the ADC122S051/ADC122S051Q will be referred to as the ADC122S051.

The ADC122S051 is a successive-approximation analog-to-digital converter designed around a charge-redistribution digital-to-analog converter. Simplified schematics of the ADC122S051 in both track and hold modes are shown in Figures 1, 2, respectively. In Figure 1, the ADC122S051 is in track mode: switch SW1 connects the sampling capacitor to one of two analog input channels through the multiplexer, and SW2 balances the comparator inputs. The ADC122S051 is in this state for the first three SCLK cycles after \overline{CS} is brought low.



20106409

FIGURE 1. ADC122S051 in Track Mode



20106410

FIGURE 2. ADC122S051 in Hold Mode

2.0 USING THE ADC122S051

An ADC122S051 timing diagram and a serial interface timing diagram for the ADC122S051 are shown in the Timing Diagrams section. \overline{CS} is chip select, which initiates conversions and frames the serial data transfers. SCLK (serial clock) controls both the conversion process and the timing of serial data. DOUT is the serial data output pin, where a conversion result is sent as a serial data stream, MSB first. Data to be written to the ADC122S051's Control Register is placed at DIN, the serial data input pin. New data is written to DIN with each conversion.

A serial frame is initiated on the falling edge of \overline{CS} and ends on the rising edge of \overline{CS} . Each frame must contain an integer multiple of 16 rising SCLK edges. The ADC output data (DOUT) is in a high impedance state when \overline{CS} is high and is active when \overline{CS} is low. Thus, \overline{CS} acts as an output enable. Additionally, the device goes into a power down state when \overline{CS} is high and also between continuous conversion cycles.

Figure 2 shows the ADC122S051 in hold mode: switch SW1 connects the sampling capacitor to ground, maintaining the sampled voltage, and switch SW2 unbalances the comparator. The control logic then instructs the charge-redistribution DAC to add fixed amounts of charge to the sampling capacitor until the comparator is balanced. When the comparator is balanced, the digital word supplied to the DAC is the digital representation of the analog input voltage. The ADC122S051 is in this state for the fourth through sixteenth SCLK cycles after \overline{CS} is brought low.

The time when \overline{CS} is low is considered a serial frame. Each of these frames should contain an integer multiple of 16 SCLK cycles, during which time a conversion is performed and clocked out at the DOUT pin and data is clocked into the DIN pin to indicate the multiplexer address for the next conversion.

During the first 3 cycles of SCLK, the ADC is in the track mode, acquiring the input voltage. For the next 13 SCLK cycles the conversion is accomplished and the data is clocked out, MSB first, starting on the 5th clock. If there are more than one conversion in a frame, the ADC will re-enter the track mode on the falling edge of SCLK after the $N*16$ th rising edge of SCLK, and re-enter the hold/convert mode on the $N*16+4$ th falling edge of SCLK, where "N" is an integer.

When \overline{CS} is brought high, SCLK is internally gated off. If SCLK is stopped in the low state while \overline{CS} is high, the subsequent fall of \overline{CS} will generate a falling edge of the internal version of SCLK, putting the ADC into the track mode. This is seen by the ADC as the first falling edge of SCLK. If SCLK is stopped with SCLK high, the ADC enters the track mode on the first falling edge of SCLK after the falling edge of \overline{CS} .

During each conversion, data is clocked into the ADC at DIN on the first 8 rising edges of SCLK after the fall of \overline{CS} . For each conversion, it is necessary to clock in the data indicating

the input that is selected for the conversion after the current one. See Tables 1, 2 and [Table 3](#).

If $\overline{\text{CS}}$ and SCLK go low within the times defined by t_{CSU} and t_{CLH} , the rising edge of SCLK that begins clocking data in at DIN may be one clock cycle later than expected. It is, therefore, best to strictly observe the minimum t_{CSU} and t_{CLH} times given in the Timing Specifications.

There are no power-up delays or dummy conversions required with the ADC122S051. The ADC is able to sample and convert an input to full conversion immediately following power up. The first conversion result after power-up will be that of IN1.

TABLE 1. Control Register Bits

Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
DONTC	DONTC	ADD2	ADD1	ADD0	DONTC	DONTC	DONTC

TABLE 2. Control Register Bit Descriptions

Bit #:	Symbol:	Description
7 - 6, 2 - 0	DONTC	Don't care. The value of these bits do not affect the device.
3	ADD0	These three bits determine which input channel will be sampled and converted in the next track/hold cycle. The mapping between codes and channels is shown in Table 3 .
4	ADD1	
5	ADD2	

TABLE 3. Input Channel Selection

ADD2	ADD1	ADD0	Input Channel
x	0	0	IN1 (Default)
x	0	1	IN2
x	1	x	Not allowed. The output signal at the D _{OUT} pin is indeterminate if ADD1 is high.

3.0 ADC122S051 TRANSFER FUNCTION

The output format of the ADC122S051 is straight binary. Code transitions occur midway between successive integer LSB values. The LSB width for the ADC122S051 is $V_A/4096$.

The ideal transfer characteristic is shown in *Figure 3*. The transition from an output code of 0000 0000 0000 to a code of 0000 0000 0001 is at $1/2$ LSB, or a voltage of $V_A/8192$. Other code transitions occur at steps of one LSB.

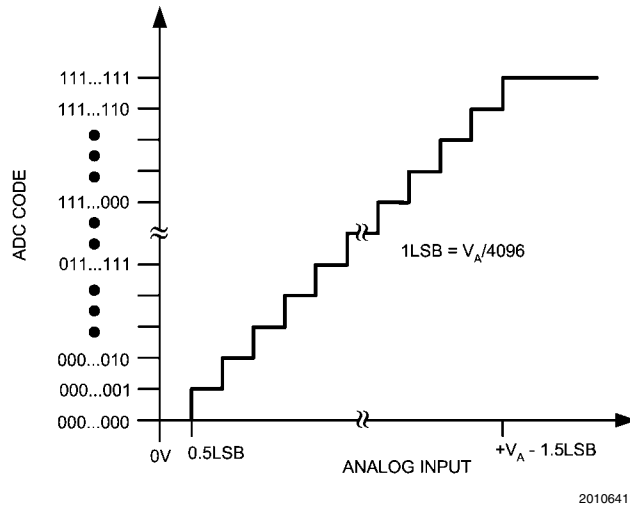


FIGURE 3. Ideal Transfer Characteristic

4.0 TYPICAL APPLICATION CIRCUIT

A typical application of the ADC122S051 is shown in *Figure 4*. Power is provided, in this example, by the National Semiconductor LP2950 low-dropout voltage regulator, available in a variety of fixed and adjustable output voltages. The power supply pin is bypassed with a capacitor network located close to the ADC122S051. Because the reference for the ADC122S051 is the supply voltage, any noise on the supply

will degrade device noise performance. To keep noise off the supply, use a dedicated linear regulator for this device, or provide sufficient decoupling from other circuitry to keep noise off the ADC122S051 supply pin. Because of the ADC122S051's low power requirements, it is also possible to use a precision reference as a power supply to maximize performance. The four-wire interface is shown connected to a microprocessor or DSP.

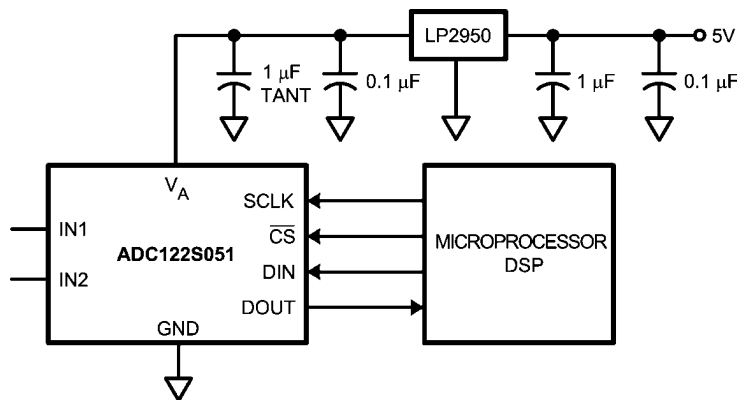


FIGURE 4. Typical Application Circuit

5.0 ANALOG INPUTS

An equivalent circuit for one of the ADC122S051's input channels is shown in [Figure 5](#). Diodes D1 and D2 provide ESD protection for the analog inputs. At no time should any input go beyond ($V_A + 300$ mV) or ($GND - 300$ mV), as these ESD diodes will begin conducting, which could result in erratic operation. For this reason, these ESD diodes should NOT be used to clamp the input signal.

The capacitor C1 in [Figure 5](#) has a typical value of 3 pF, and is mainly the package pin capacitance. Resistor R1 is the on-resistance of the multiplexer and track / hold switch, and is typically 500 ohms. Capacitor C2 is the ADC122S051 sampling capacitor and is typically 30 pF. The ADC122S051 will deliver best performance when driven by a low-impedance source to eliminate distortion caused by the charging of the sampling capacitance. This is especially important when using the ADC122S051 to sample AC signals. Also important when sampling dynamic signals is a band-pass or low-pass filter to reduce harmonics and noise, improving dynamic performance.

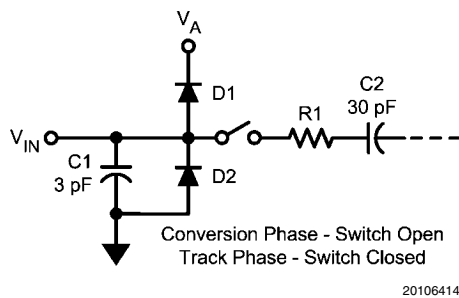


FIGURE 5. Equivalent Input Circuit

6.0 DIGITAL INPUTS AND OUTPUTS

The ADC122S051's digital output DOUT is limited by, and cannot exceed, the supply voltage, V_A . The digital input pins are not prone to latch-up and, although not recommended, SCLK, \overline{CS} and DIN may be asserted before V_A without any latch-up risk.

7.0 POWER SUPPLY CONSIDERATIONS

The ADC122S051 is fully powered-up whenever \overline{CS} is low, and fully powered-down whenever \overline{CS} is high, with one exception: the ADC122S051 automatically enters power-down mode between the 16th falling edge of a conversion and the 1st falling edge of the subsequent conversion (see Timing Diagrams).

The ADC122S051 can perform multiple conversions back to back; each conversion requires 16 SCLK cycles. The ADC122S051 will perform conversions continuously as long as \overline{CS} is held low.

The user may trade off throughput for power consumption by simply performing fewer conversions per unit time. The Power Consumption vs. Sample Rate curve in the Typical Performance Curves section shows the typical power consumption of the ADC122S051 versus throughput. To calculate the power consumption, simply multiply the fraction of time spent in the normal mode by the normal mode power consumption, and add the fraction of time spent in shutdown mode multiplied by the shutdown mode power dissipation.

7.1 Power Management

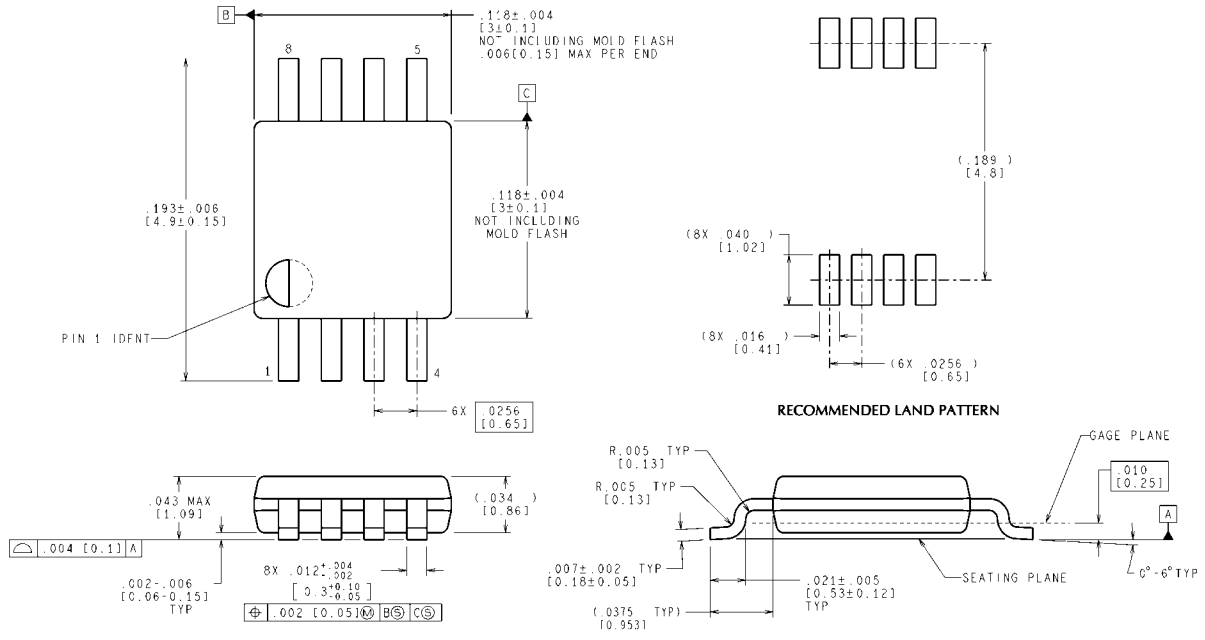
When the ADC122S051 is operated continuously in normal mode, the maximum throughput is $f_{SCLK}/16$. Throughput may be traded for power consumption by running f_{SCLK} at its maximum 8 MHz and performing fewer conversions per unit time, putting the ADC122S051 into shutdown mode between conversions. A plot of typical power consumption versus throughput is shown in the Typical Performance Curves section. To calculate the power consumption for a given throughput, multiply the fraction of time spent in the normal mode by the normal mode power consumption and add the fraction of time spent in shutdown mode multiplied by the shutdown mode power consumption. Generally, the user will put the part into normal mode and then put the part back into shutdown mode. Note that the curve of power consumption vs. throughput is nearly linear. This is because the power consumption in the shutdown mode is so small that it can be ignored for all practical purposes.

7.2 Power Supply Noise Considerations

The charging of any output load capacitance requires current from the power supply, V_A . The current pulses required from the supply to charge the output capacitance will cause voltage variations on the supply. If these variations are large enough, they could degrade SNR and SINAD performance of the ADC. Furthermore, discharging the output capacitance when the digital output goes from a logic high to a logic low will dump current into the die substrate, which is resistive. Load discharge currents will cause "ground bounce" noise in the substrate that will degrade noise performance if that current is large enough. The larger is the output capacitance, the more current flows through the die substrate and the greater is the noise coupled into the analog channel, degrading noise performance.

To keep noise out of the power supply, keep the output load capacitance as small as practical. If the load capacitance is greater than 35 pF, use a 100 Ω series resistor at the ADC output, located as close to the ADC output pin as practical. This will limit the charge and discharge current of the output capacitance and improve noise performance.

Physical Dimensions inches (millimeters) unless otherwise noted



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MUA08A (Rev F)

8-Lead MSOP
Order Number ADC122S051CIMM, ADC122S051CIMMX, ADC122S051QIMM, ADC122S051QIMMX
NS Package Number P0MUA08A

Notes

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2012, Texas Instruments Incorporated